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# INTERNATIONAL STANDARD



## Field Device Integration (FDI®) – Part 4: FDI Packages

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

### FIELD DEVICE INTEGRATION (FDI®) –

#### Part 4: FDI® Packages

#### FOREWORD

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IEC 62769-4 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2021. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) added DocumentClass to Package Schema, Description of Feature Table and Documentation Catalog, individual schemas for Feature Table and Package Documentation Catalog, schema for UnitConversion, interactive download to device, and Feature Unit Conversion;
- b) moved DocumentClass to Package Documentation Catalog Schema;
- c) updated Description of Feature Table updated XML schema for Feature Table.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/857/CDV	65E/914/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/standardsdev/publications](http://www.iec.ch/standardsdev/publications).

A list of all parts in the IEC 62769 series, published under the general title *Field device integration (FDI®)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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## INTRODUCTION

The IEC 62769 series has the general title *Field Device Integration (FDI)* and the following parts:

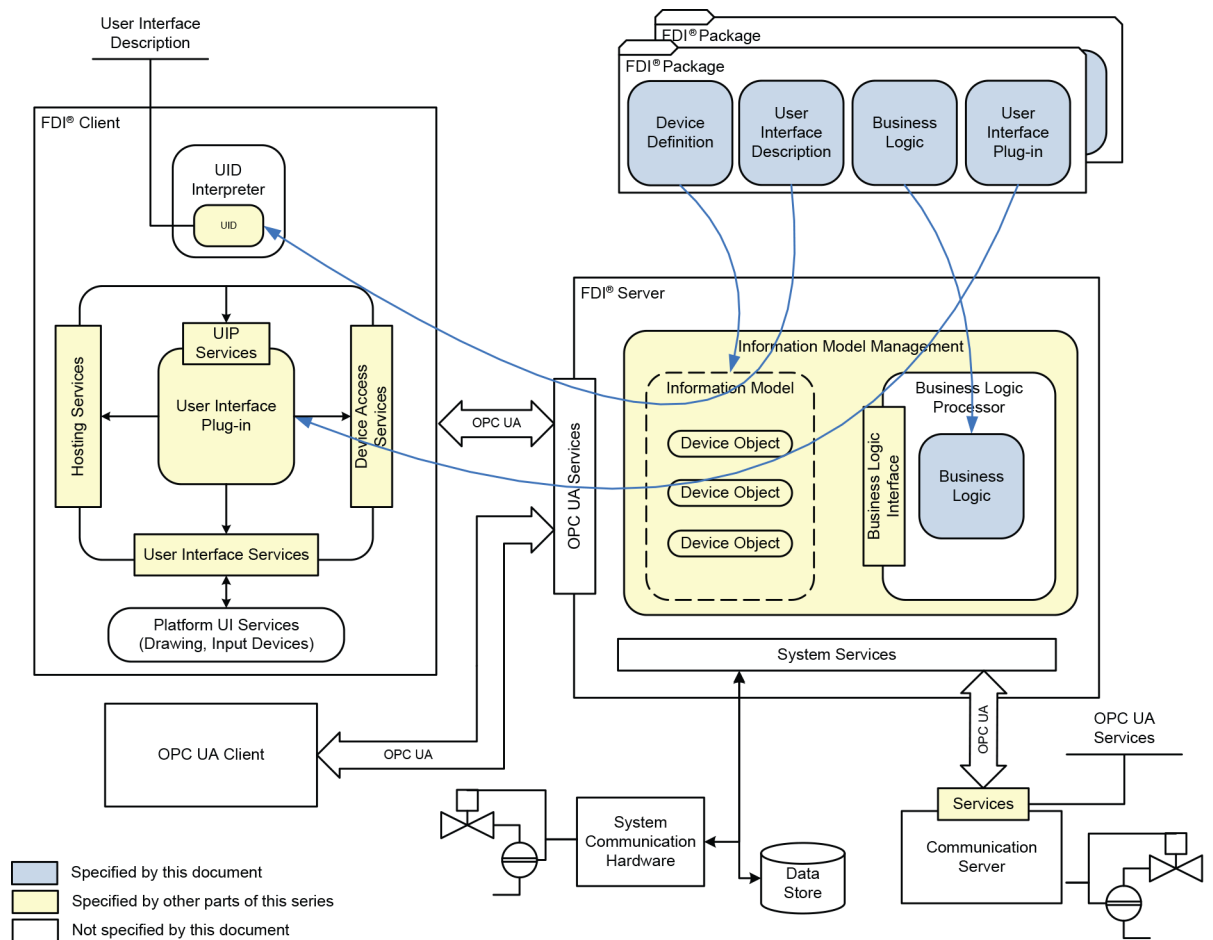
- Part 1: Overview
- Part 2: FDI Client
- Part 3: FDI Server
- Part 4: FDI Packages
- Part 5: FDI Information Model
- Part 6: FDI Technology Mapping
- Part 7: FDI Communication Devices
- Part 100: Profiles — Generic Protocol Extensions
- Part 101-1: Profiles — Foundation Fieldbus H1
- Part 101-2: Profiles — Foundation Fieldbus HSE
- Part 103-1: Profiles — PROFIBUS
- Part 103-4: Profiles — PROFINET
- Part 109-1: Profiles — HART and WirelessHART
- Part 115-2: Profiles — Protocol-specific Definitions for Modbus RTU
- Part 150-1: Profiles — ISA 100.11a

# FIELD DEVICE INTEGRATION (FDI®) –

## Part 4: FDI® Packages

### 1 Scope

This part of IEC 62769 specifies the FDI<sup>®1</sup> Packages. The overall FDI<sup>®</sup> architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this figure.



**Figure 1 – FDI® architecture diagram**

### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies.

<sup>1</sup> FDI<sup>®</sup> is a registered trademark of the non-profit organization Fieldbus Foundation, Inc. This information is given for the convenience of users of this document and does not constitute an endorsement by IEC of the trademark holder or any of its products. Compliance does not require use of the trade name. Use of the trade name requires permission of the trade name holder.

For undated references, the latest edition of the referenced document (including any amendments) applies.

~~IEC 61804 (all parts), Function blocks (FB) for process control and electronic device description language (EDDL)~~

IEC 61804-3, *Devices and integration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL) – Part 3: EDDL syntax and semantics*

IEC 61804-5:20152020, *Devices and intergration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL) – Part 5: EDDL Built-in library*

IEC 62769-1, *Field Device Integration (FDI®) – Part 1: Overview*

IEC 62769-2, *Field Device Integration (FDI®) – Part 2: Client*

IEC 62769-5, *Field Device Integration (FDI®) – Part 5: FDI® Information Model*

IEC 62769-6, *Field Device Integration (FDI®) – Part 6: FDI® Technology Mappings*

IEC 62769-7, *Field Device Integration (FDI®) – Part 7: Communication Devices*

IEC 62769-1xx (all parts), *Field Device Integration (FDI®) – Part 1xx-y: Profiles*

ISO/IEC 11578, *Information technology – Open Systems Interconnection – Remote Procedure Call (RPC)*

ISO/IEC 29500-2:20162021, ~~Information technology~~ – *Document description and processing languages – Office Open XML file formats – Part 2: Open packaging conventions*

ISO 639-1, *Codes for the representation of names of languages – Part 1: Alpha-2 code*

ISO 32000-1, *Document management – Portable document format – Part 1: PDF 1.7*

Dublin Core Metadata Initiative: DCMI Metadata Terms, 2020

FCG TS10099, *Field Device Integration (FDI®) – Technology Management*

FIPS 140-3:2019, *Security Requirements for Cryptographic Modules*

~~Extensible Markup Language (XML) 1.0, W3C Recommendation, available at <<http://www.w3.org/TR/REC-xml/>>~~

~~XML Schema Definition Language (XSD) 1.1, W3C Recommendation, available at <<http://www.w3.org/TR/xmlschema11-1/>>~~

~~FIPS 140-2, Security Requirements for Cryptographic Modules~~

ETSI EN 319 132-1, *Electronic Signatures and Infrastructures (ESI); XAdES digital signatures; Part 1: Building blocks and XAdES baseline signatures*

ETSI TS 101 733, *Electronic Signatures and Infrastructures (ESI); CMS Advanced Electronic Signatures (CAAdES)*

# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



**Field Device Integration (FDI®) –  
Part 4: FDI Packages**

**Intégration des appareils de terrain (FDI®) –  
Partie 4: Paquetages FDI**

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

### FIELD DEVICE INTEGRATION (FDI®) –

#### Part 4: FDI® Packages

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IEC 62769-4 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2021. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) added DocumentClass to Package Schema, Description of Feature Table and Documentation Catalog, individual schemas for Feature Table and Package Documentation Catalog, schema for UnitConversion, interactive download to device, and Feature Unit Conversion;
- b) moved DocumentClass to Package Documentation Catalog Schema;
- c) updated Description of Feature Table updated XML schema for Feature Table.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/857/CDV	65E/914/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/standardsdev/publications](http://www.iec.ch/standardsdev/publications).

A list of all parts in the IEC 62769 series, published under the general title *Field device integration (FDI<sup>®</sup>)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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# FIELD DEVICE INTEGRATION (FDI®) – Part 4: FDI® Packages

## 1 Scope

This part of IEC 62769 specifies the FDI<sup>®1</sup> Packages. The overall FDI<sup>®</sup> architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this figure.

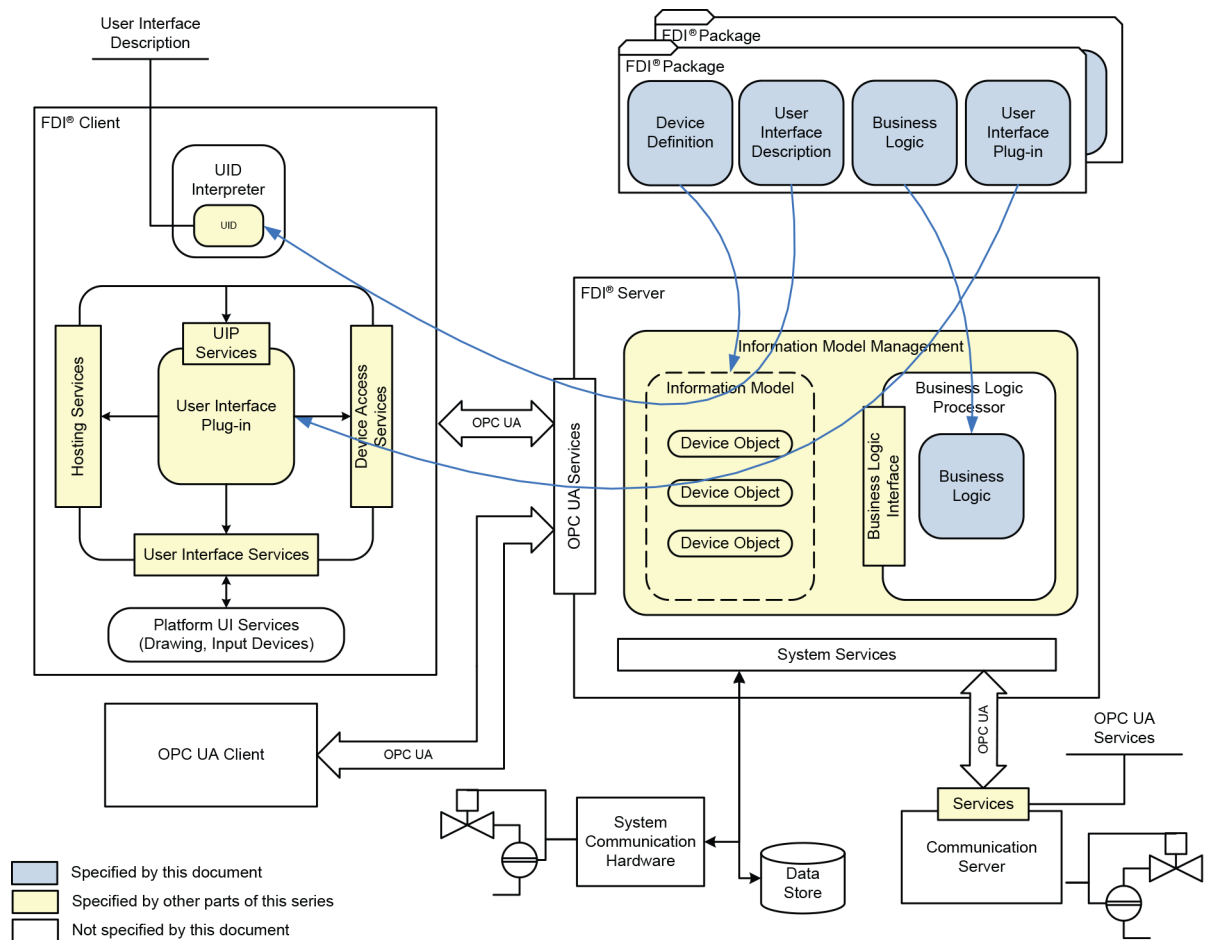


Figure 1 – FDI<sup>®</sup> architecture diagram

## 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies.

<sup>1</sup> FDI<sup>®</sup> is a registered trademark of the non-profit organization Fieldbus Foundation, Inc. This information is given for the convenience of users of this document and does not constitute an endorsement by IEC of the trademark holder or any of its products. Compliance does not require use of the trade name. Use of the trade name requires permission of the trade name holder.

For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61804-3, *Devices and integration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL) – Part 3: EDDL syntax and semantics*

IEC 61804-5:2020, *Devices and intergration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL) – Part 5: EDDL Builtin library*

IEC 62769-1, *Field Device Integration (FDI®) – Part 1: Overview*

IEC 62769-2, *Field Device Integration (FDI®) – Part 2: Client*

IEC 62769-5, *Field Device Integration (FDI®) – Part 5: FDI® Information Model*

IEC 62769-6, *Field Device Integration (FDI®) – Part 6: FDI® Technology Mappings*

IEC 62769-7, *Field Device Integration (FDI®) – Part 7: Communication Devices*

IEC 62769-1xx (all parts), *Field Device Integration (FDI®) – Part 1xx-y: Profiles*

ISO/IEC 11578, *Information technology – Open Systems Interconnection – Remote Procedure Call (RPC)*

ISO/IEC 29500-2:2021, *Document description and processing languages – Office Open XML file formats – Part 2: Open packaging conventions*

ISO 639-1, *Codes for the representation of names of languages – Part 1: Alpha-2 code*

ISO 32000-1, *Document management – Portable document format – Part 1: PDF 1.7*

Dublin Core Metadata Initiative: DCMI Metadata Terms, 2020

FCG TS10099, *Field Device Integration (FDI®) – Technology Management*

FIPS 140-3:2019, *Security Requirements for Cryptographic Modules*

ETSI EN 319 132-1, *Electronic Signatures and Infrastructures (ESI); XAdES digital signatures; Part 1: Building blocks and XAdES baseline signatures*

ETSI TS 101 733, *Electronic Signatures and Infrastructures (ESI); CMS Advanced Electronic Signatures (CAAdES)*

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### INTÉGRATION DES APPAREILS DE TERRAIN (FDI®) –

#### Partie 4: Paquetages FDI®

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L'IEC 62769-4 a été établie par le sous-comité 65E: Les dispositifs et leur intégration dans les systèmes de l'entreprise, du comité d'études 65 de l'IEC: Mesure, commande et automation dans les processus industriels. Il s'agit d'une Norme internationale.

Cette troisième édition annule et remplace la deuxième édition parue en 2021. Cette édition constitue une révision technique.

Cette édition inclut les modifications techniques majeures suivantes par rapport à l'édition précédente:

- a) ajout de DocumentClass à Schéma du Paquetage, Description de la Table des Fonctionnalités et Catalogue de Documentation, de schémas individuels pour la Table des fonctionnalités et le Catalogue de Documentation de Paquetage, d'un schéma pour UnitConversion, de téléchargement interactif vers l'appareil et de Fonctionnalité de Conversion d'Unités;

- b) transfert de DocumentClass dans Schéma du Catalogue de Documentation de Paquetage;
- c) mise à jour de la Description de la Table des Fonctionnalités et du schéma XML de la Table des Fonctionnalités.

Le texte de cette Norme internationale est issu des documents suivants:

Projet	Rapport de vote
65E/857/CDV	65E/914/RVC

Le rapport de vote indiqué dans le tableau ci-dessus donne toute information sur le vote ayant abouti à son approbation.

La langue employée pour l'élaboration de cette Norme internationale est l'anglais.

Ce document a été rédigé selon les Directives ISO/IEC, Partie 2, il a été développé selon les Directives ISO/IEC, Partie 1 et les Directives ISO/IEC, Supplément IEC, disponibles sous [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). Les principaux types de documents développés par l'IEC sont décrits plus en détail sous [www.iec.ch/standardsdev/publications](http://www.iec.ch/standardsdev/publications).

Une liste de toutes les parties de la série IEC 62769, publiées sous le titre général *Intégration des appareils de terrain (FDI®)*, se trouve sur le site web de l'IEC.

Le comité a décidé que le contenu de ce document ne sera pas modifié avant la date de stabilité indiquée sur le site web de l'IEC sous [webstore.iec.ch](http://webstore.iec.ch) dans les données relatives au document recherché. A cette date, le document sera

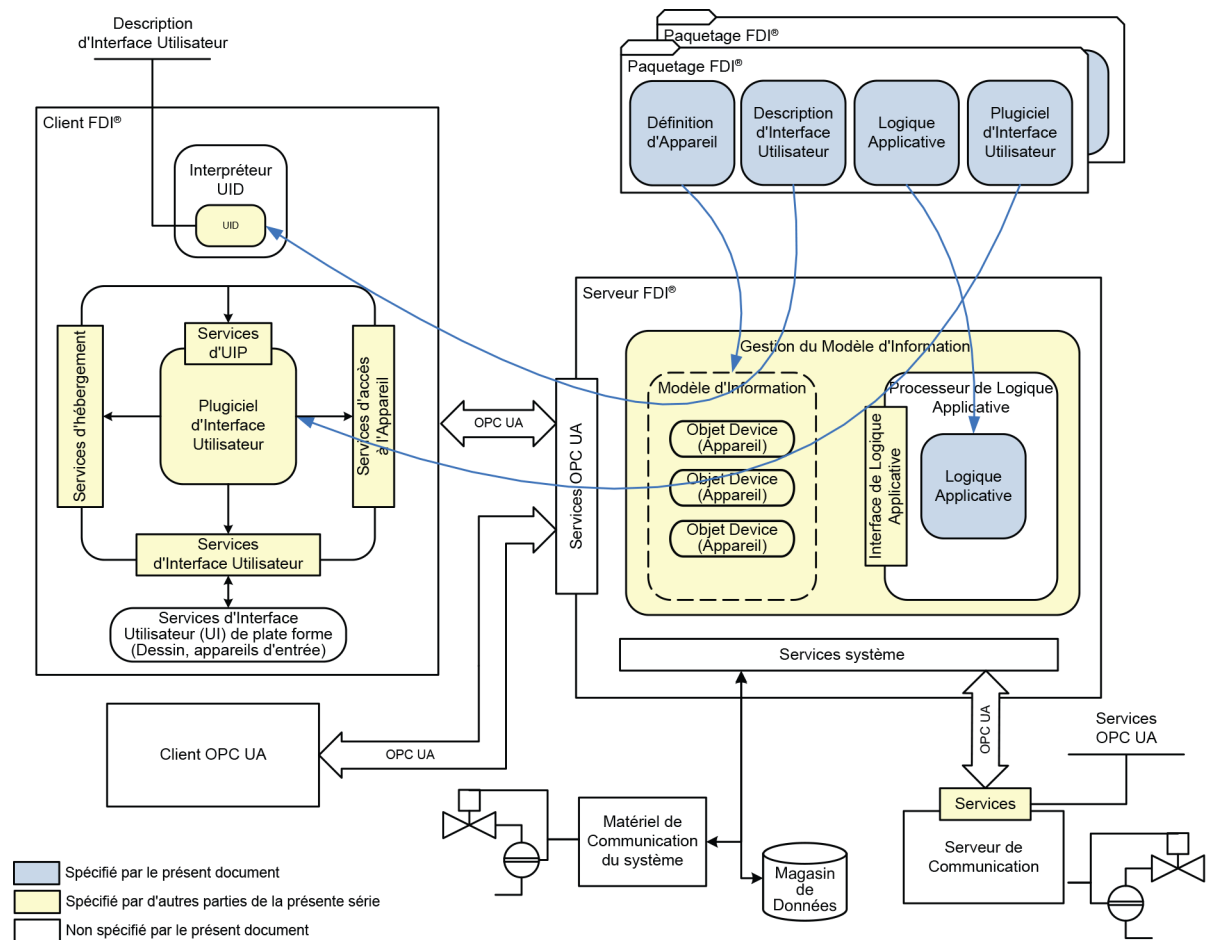
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# INTÉGRATION DES APPAREILS DE TERRAIN (FDI®) – Partie 4: Paquetages FDI®

## 1 Domaine d'application

La présente partie de l'IEC 62769 spécifie les Paquetages FDI®<sup>1</sup>. L'architecture FDI® complète est représentée à la Figure 1. Les composants architecturaux qui relèvent du domaine d'application du présent document ont été mis en évidence dans cette figure.



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Figure 1 – Diagramme de l'architecture FDI®

## 2 Références normatives

Les documents suivants sont cités dans le texte de sorte qu'ils constituent, pour tout ou partie de leur contenu, des exigences du présent document. Pour les références datées, seule

<sup>1</sup> FDI® est une marque déposée de l'organisation à but non lucratif Fieldbus Foundation, Inc. Cette information est donnée à l'intention des utilisateurs du présent document et ne signifie nullement que l'IEC approuve le détenteur de la marque ou l'emploi de ses produits. La conformité n'exige pas l'utilisation de la marque. L'utilisation de la marque exige l'autorisation du détenteur de la marque.



l'édition citée s'applique. Pour les références non datées, la dernière édition du document de référence s'applique (y compris les éventuels amendements).

IEC 61804-3, *Les dispositifs et leur intégration dans les systèmes de l'entreprise – Blocs fonctionnels (FB) pour les procédés industriels et le langage de description électronique de produits (EDDL) – Partie 3: Sémantique et syntaxe EDDL*

IEC 61804-5:2020, *Les dispositifs et leur intégration dans les systèmes de l'entreprise – Blocs fonctionnels (FB) pour les procédés industriels et le langage de description électronique de produit (EDDL) – Partie 5: Bibliothèque de Built-in EDDL*

IEC 62769-1, *Intégration des appareils de terrain (FDI®) – Partie 1: Vue d'ensemble*

IEC 62769-2, *Intégration des appareils de terrain (FDI®) – Partie 2: Client*

IEC 62769-5, *Intégration des appareils de terrain (FDI®) – Partie 5: Modèle d'Information FDI®*

IEC 62769-6, *Intégration des appareils de terrain (FDI®) – Partie 6: Mappings de technologies FDI®*

IEC 62769-7, *Intégration des appareils de terrain (FDI®) – Partie 7: Appareils de communication*

IEC 62769-1xx (toutes les parties), *Intégration des appareils de terrain (FDI®) – Partie 1xx-y: Profils*

ISO/IEC 11578, *Information technology – Open Systems Interconnection – Remote Procedure Call (RPC)* (disponible en anglais seulement)

ISO/IEC 29500-2:2021, *Document description and processing languages – Office Open XML file formats – Part 2: Open packaging conventions* (disponible en anglais seulement)

ISO 639-1, *Codes pour la représentation des noms de langue – Partie 1: Code alpha-2*

ISO 32000-1, *Gestion de documents – Format de document portable – Partie 1: PDF 1.7*

Dublin Core Metadata Initiative: DCMI Metadata Terms, 2020 (disponible en anglais seulement)

FCG TS10099, *Field Device Integration (FDI®) – Technology Management* (disponible en anglais seulement)

FIPS 140-3:2019, *Security Requirements for Cryptographic Modules* (disponible en anglais seulement)

ETSI EN 319 132-1, *Electronic Signatures and Infrastructures (ESI); XAdES digital signatures; Part 1: Building blocks and XAdES baseline signatures* (disponible en anglais seulement)

ETSI TS 101 733, *Electronic Signatures and Infrastructures (ESI); CMS Advanced Electronic Signatures (CAAdES)* (disponible en anglais seulement)